Title of Invention

THERMOSETTING RESIN COMPOSITION, FILM-FORM ADHESIVE, ADHESIVE SHEET, AND METHOD FOR PRODUCING SEMICONDUCTOR DEVICE

ABSTRACT

Disclosed is a thermosetting resin composition containing an epoxy resin, a curing agent, a first elastomer having a weight average molecular weight of 200,000 to 1,300,000 and having at least one functional group selected from the group consisting of a carboxy group and a hydroxyl group, and a second elastomer having a weight average molecular weight of 200,000 to 1,300,000 and having neither a carboxy group nor a hydroxyl group, in which the content of the sum of the first elastomer and the second elastomer is 40% by mass or less based on the total amount of the thermosetting resin composition.

Figure 7